



XTMF120N03F

1200V N-ch Planar MOSFET

Product Description

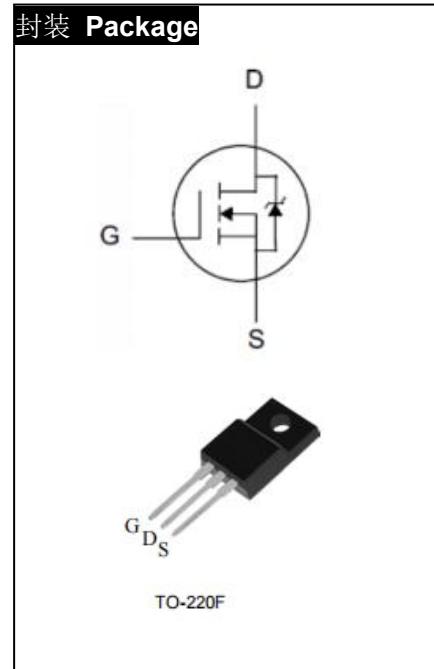
BV _{DSS}	1200	V
I _D	3	A
R _{DSON} ,Typ.	6	Ω

General Features

- RoHS Compliant
- R_{DSON},typ.=6Ω@V_{GS}=10V
- Fast Recovery Body Diode
- Low Gate Charge Minimize Switching Loss

Applications

- Adaptor
- Charger
- SMPS Standby Power



Absolute Maximum Ratings T_j=25°C

Symbol	Parameter	XTMF120N03F	Unit
V _{DSS}	Drain-to-Source Voltage	1200	V
V _{GSS}	Gate-to-Source Voltage	±30	
I _D	Continuous Drain Current	3.0	A
I _{DM}	Pulsed Drain Current at V _{GS} =10V	12	
E _{AS}	Single Pulse Avalanche Energy	100	mJ
P _D	Power Dissipation	30	W
	Derating Factor above 25°C	0.24	W/ °C
T _L	Soldering Temperature Distance of 1.6mm from case for 10 seconds	300	°C
T _J &T _{STG}	Operating and Storage Temperature Range	-55 to 150	



Caution: Stresses greater than those listed in the "Absolute Maximum Ratings" may cause permanent damage to the device.

Thermal Characteristics

Symbol	Parameter	XTMF120N03F	Unit
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case	4.17	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient	100	°C/W

Electrical Characteristics $T_j=25^\circ C$

OFF Characteristics

Symbol	Parameter	Min	Typ	Max	Unit	Test Condition
BV_{DSS}	Drain-to-Source Breakdown Voltage	1200	--	--	V	$V_{GS}=0V, I_D=250\mu A$
I_{DSS}	Drain-to-Source Leakage Current	--	--	1	uA	$V_{DS}=1200V, V_{GS}=0V$
		--	--	100		$V_{DS}=960V, V_{GS}=0V,$ $T_J = 125^\circ C$
I_{GSS}	Gate-to-Source Leakage Current	--	--	+100	nA	$V_{GS}=+30V, V_{DS}=0V$
		--	--	-100		$V_{GS}=-30V, V_{DS}=0V$

ON Characteristics

Symbol	Parameter	Min	Typ	Max	Unit	Test Condition
$R_{DS(ON)}$	Static Drain-to-Source On-Resistance	--	6.0	7.5	Ω	$V_{GS}=10V,$ $I_D=1.5A$
$V_{GS(TH)}$	Gate Threshold Voltage	2.5	--	4.5	V	$V_{DS}=V_{GS},$ $I_D=250\mu A$
g_{fs}	Forward Transconductance	--	4	--	S	$V_{DS}=20V, I_D$ $=1.5A$

**Dynamic Characteristics**

Symbol	Parameter	Min	Typ	Max	Unit	Test Condition
C_{iss}	Input Capacitance	--	860	--	pF	$V_{GS}=0V,$ $V_{DS}=25V,$ $f=1.0MHz$
C_{rss}	Reverse Transfer Capacitance	--	22	--		
C_{oss}	Output Capacitance	--	60	--		
Q_g	Total Gate Charge	--	17.5	--	nC	$V_{DD}=600V,$ $I_D=3A, V_{GS}=0 \text{ to } 10V$
Q_{gs}	Gate-to-Source Charge	--	5	--		
Q_{gd}	Gate-to-Drain (Miller) Charge	--	5.5	--		

Resistive Switching Characteristics

Symbol	Parameter	Min	Typ	Max	Unit	Test Condition
$t_{d(on)}$	Turn-on Delay Time	--	17	--	ns	$V_{DD}=600V,$ $I_D=3A,$ $V_{GS}=10V R_g=4.7\Omega$
t_{rise}	Rise Time	--	6	--		
$t_{d(off)}$	Turn-Off Delay Time	--	23	--		
t_{fall}	Fall Time	--	11	--		

Source-Drain Body Diode Characteristics

Symbol	Parameter	Min	Typ	Max	Unit	Test Condition
I_{SD}	Continuous Source Current ^[1]	--	--	3	A	Integral pn-diode in MOSFET
I_{SM}	Pulsed Source Current ^[1]	--	--	12		
V_{SD}	Diode Forward Voltage	--	--	1. 5	V	$I_S=3A,$ $V_{GS}=0V$
t_{rr}	Reverse Recovery Time	--	200	--		
Q_{rr}	Reverse Recovery Charge	--	760	--	uC	$V_{GS}=0V$ $I_F= I_S,$ $dI/dt=100A/\mu s$

[1] Pulse width $\leq 380\mu s$; duty cycle $\leq 2\%$



Typical Characteristics

Fig. 1. Output Characteristics @ $T_J = 25^\circ\text{C}$

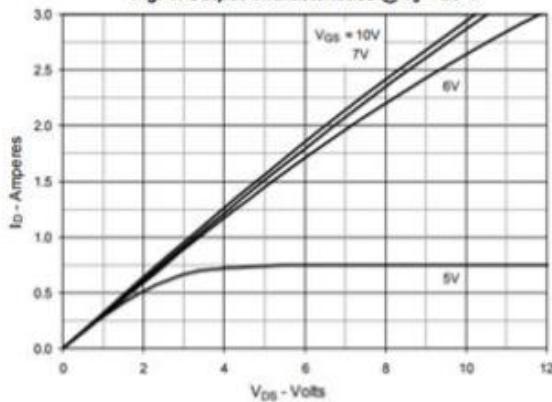


Fig. 3. Output Characteristics @ $T_J = 125^\circ\text{C}$

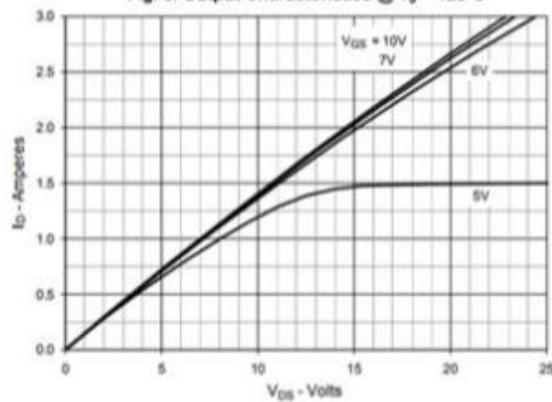


Fig. 5. $R_{DS(on)}$ Normalized to $I_D = 1.5\text{A}$ Value vs. Drain Current

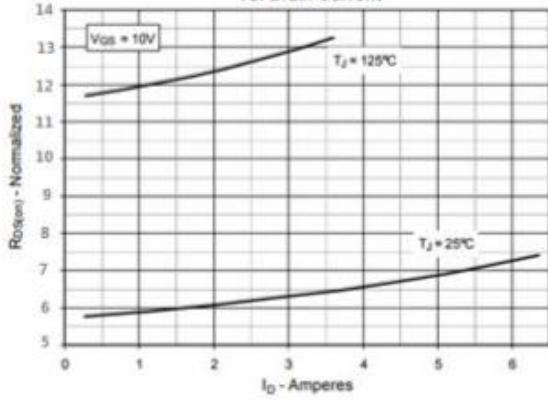


Fig. 2. Extended Output Characteristics @ $T_J = 25^\circ\text{C}$

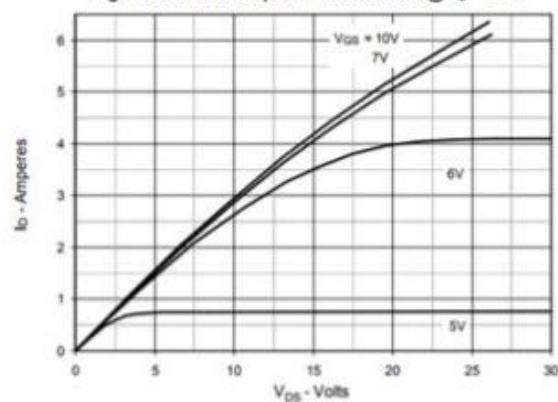


Fig. 4. $R_{DS(on)}$ Normalized to $I_D = 1.5\text{A}$ Value vs. Junction Temperature

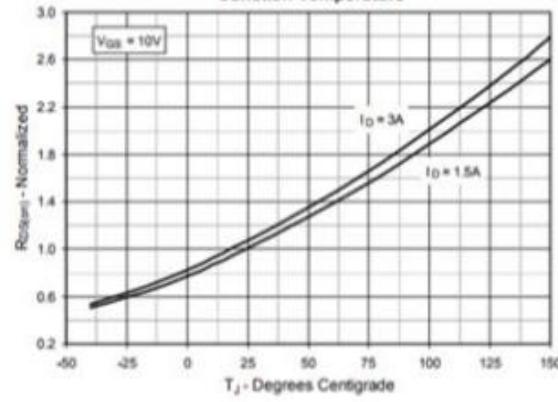
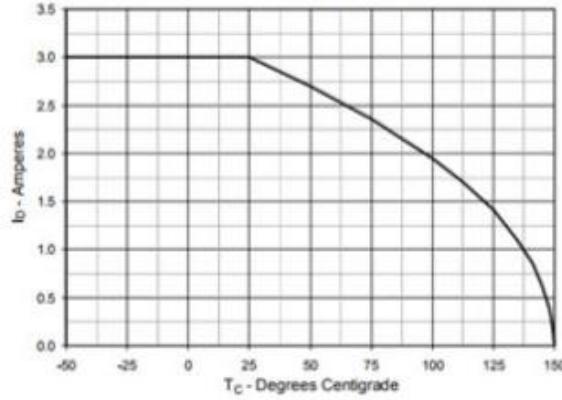
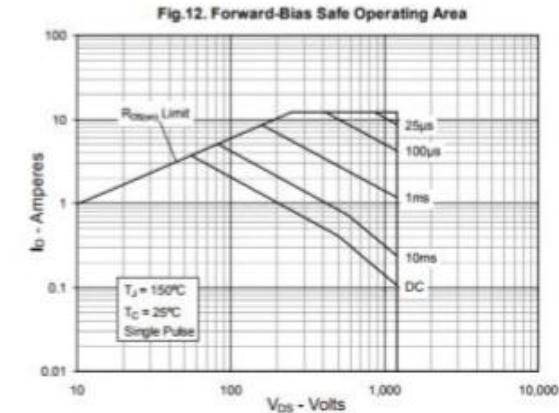
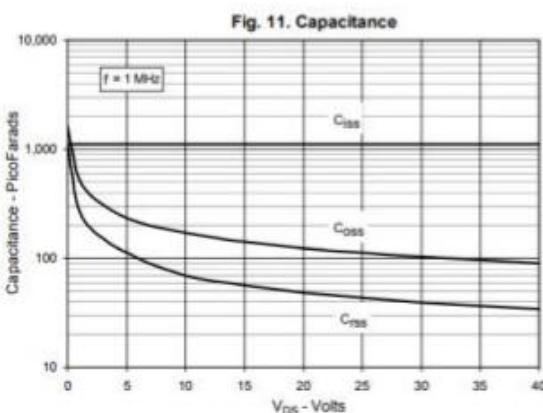
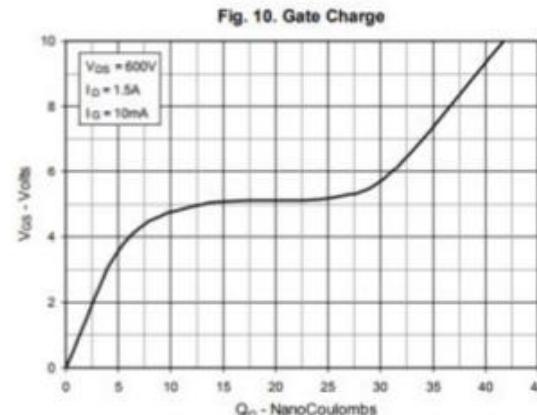
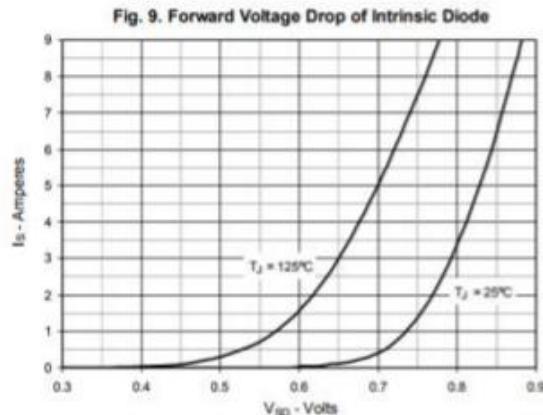
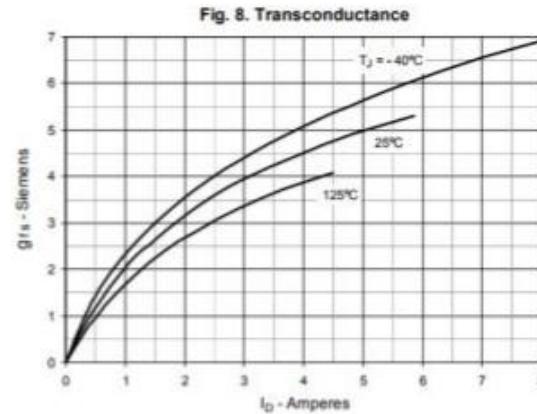
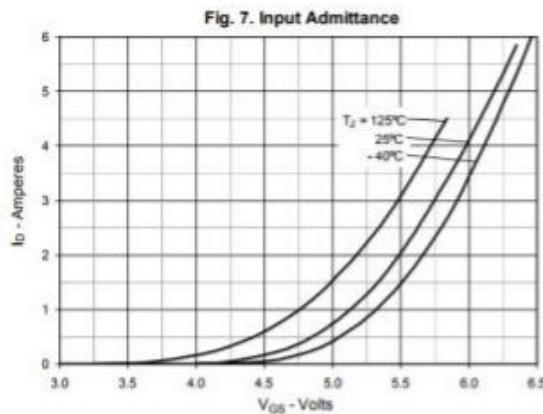


Fig. 6. Maximum Drain Current vs. Case Temperature

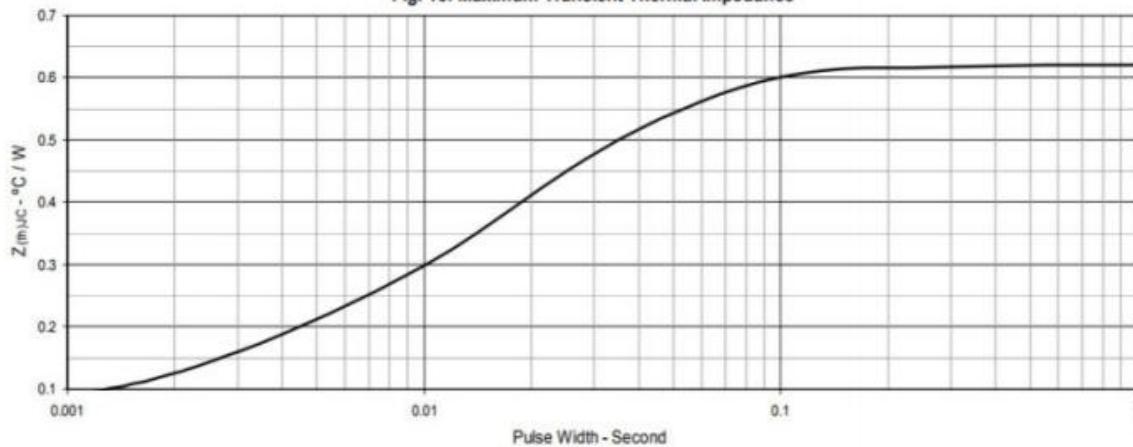




Typical Characteristics(Cont.)

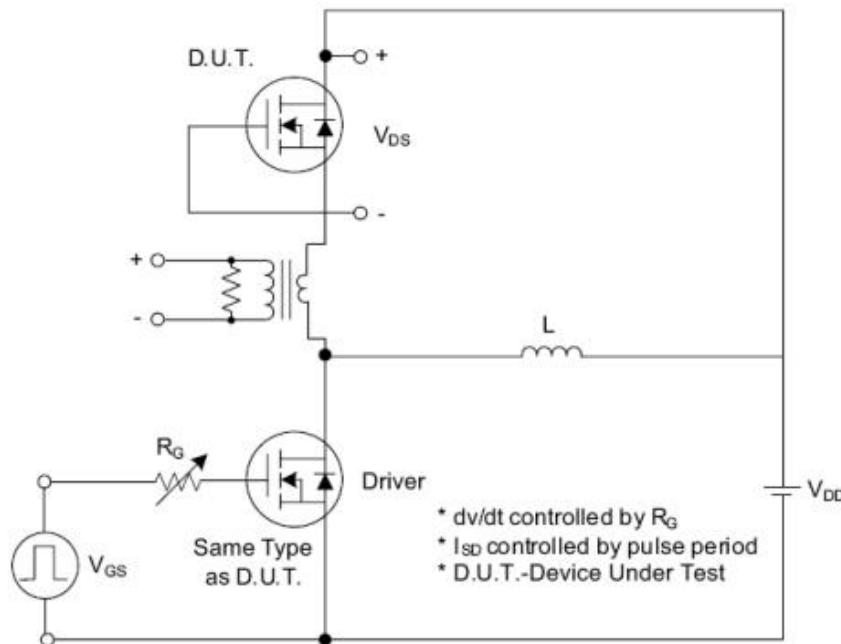
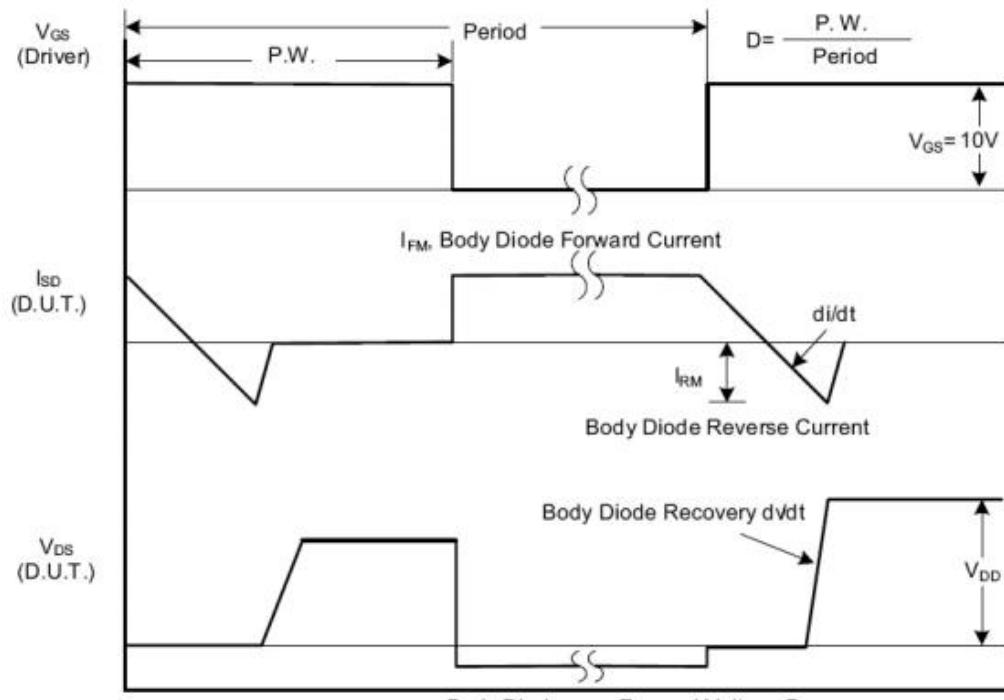




Typical Characteristics(Cont.)**Fig. 13. Maximum Transient Thermal Impedance**



Test Circuits and Waveforms

Fig. 1.1 Peak Diode Recovery dv/dt Test CircuitFig. 1.2 Peak Diode Recovery dv/dt Waveforms



Test Circuits and Waveforms (Cont.)

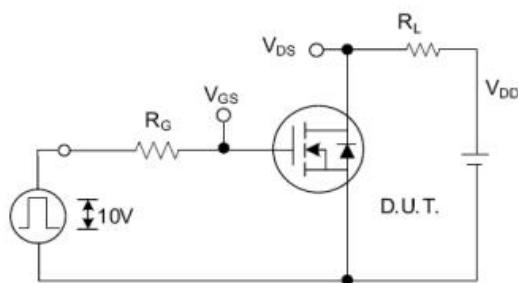


Fig. 2.1 Switching Test Circuit

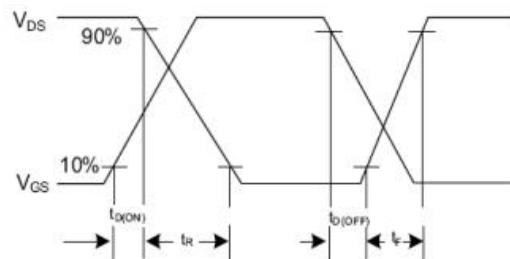


Fig. 2.2 Switching Waveforms

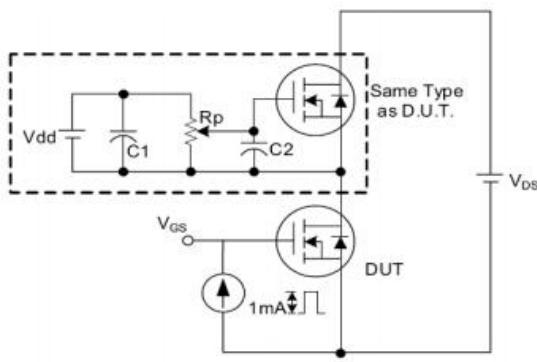


Fig. 3.1 Gate Charge Test Circuit

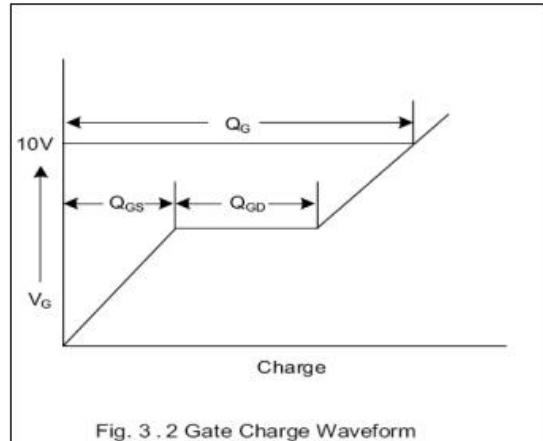


Fig. 3.2 Gate Charge Waveform

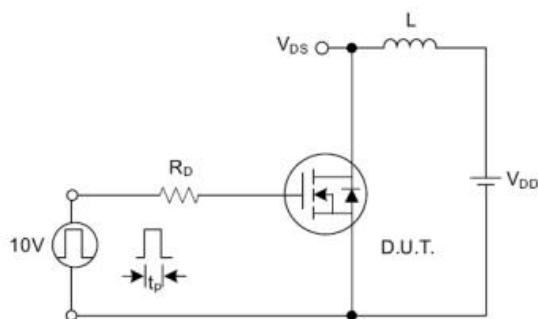


Fig. 4.1 Unclamped Inductive Switching Test Circuit

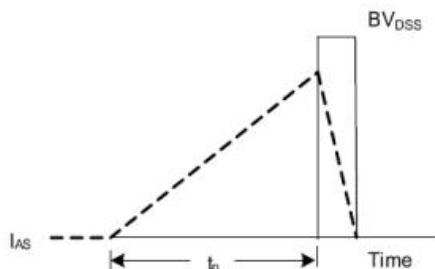


Fig. 4.2 Unclamped Inductive Switching Waveforms